

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Teck Kheng Lee

**Serial No.:** 10/829,647

**Filed:** April 22, 2004

**For:** METHODS FOR ASSEMBLY AND  
PACKAGING OF FLIP CHIP  
CONFIGURED DICE WITH INTERPOSER

**Confirmation No.:** 6967

**Examiner:** P. Perkins

**Group Art Unit:** 2822

**Attorney Docket No.:** 2269-4974.1US  
(00-0693.01/US)

VIA ELECTRONIC FILING  
February 19, 2008

**RESPONSE TO FINAL OFFICE ACTION**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The following remarks are filed in response to the Examiner's remarks in the Final Office Action mailed December 17, 2007, the three-month shortened statutory period for response to which expires on March 17, 2008. This response is submitted on or before two months from the mailing date of the Final Office Action, as February 17<sup>th</sup> was a Sunday and February 18<sup>th</sup> a Federal holiday.

**A Listing of Claims** (none being amended herein) begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.